

SKiM[®] 4

IGBT Modules

SKiM 180GD176D

Target Data

Features

- Homogeneous Si
- Trench = Trenchgate Technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_C$

Typical Applications

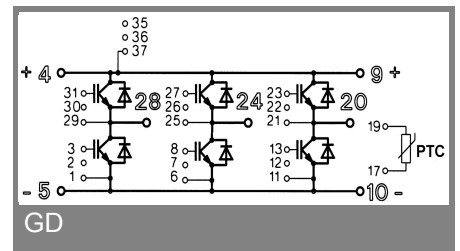
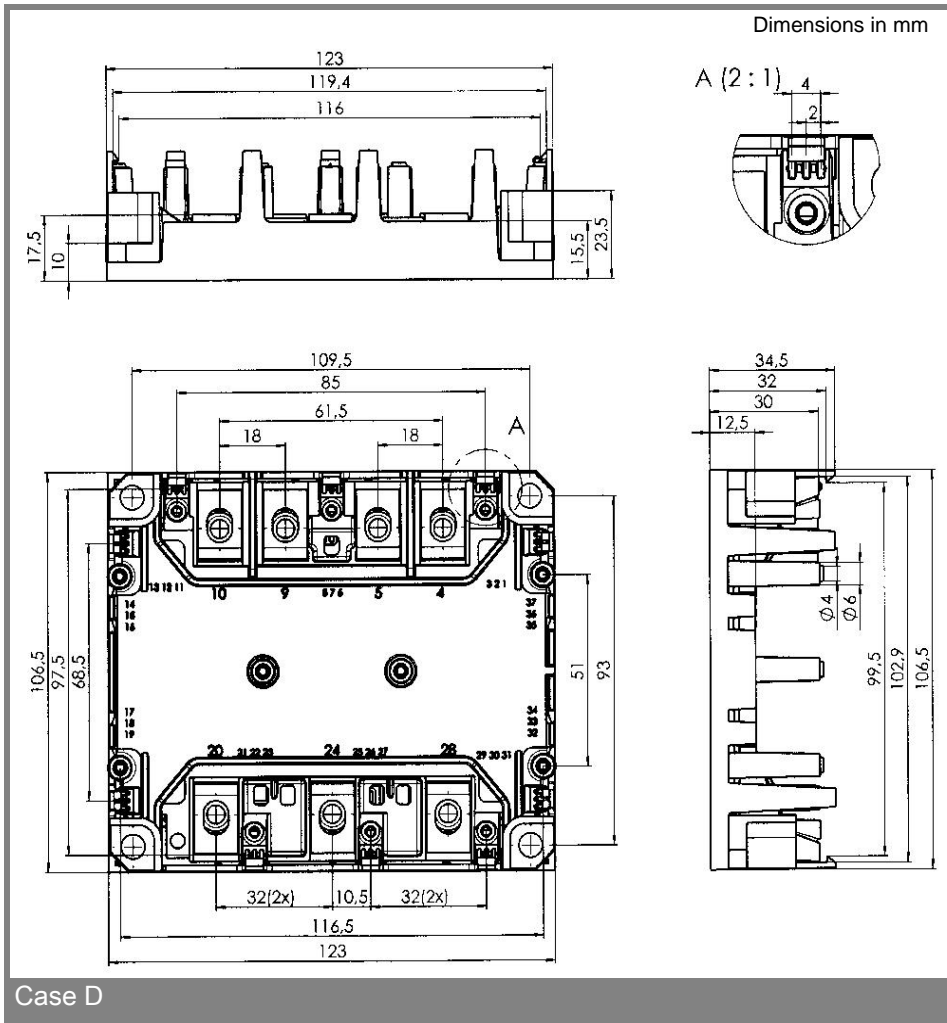
- AC inverter drives mains 575 - 750 V AC
- public transport (auxiliary syst.)

GD

Absolute Maximum Ratings		$T_{case} = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT			
V_{CES}		1700	V
I_C	$T_h = 25 (70)^\circ\text{C}$	180 (130)	A
I_{CM}	$T_h = 25 (70)^\circ\text{C}$, $t_p = 1 \text{ ms}$	360 (260)	A
V_{GES}		± 20	V
$T_j (T_{stg})$	$T_{OPERATION} \leq T_{stg}$	- 40 ... +125 $^\circ\text{C}$	$^\circ\text{C}$
V_{isol}	AC, 1 min.	4000	V
Inverse diode			
$I_F = -I_C$	$T_h = 25 (70)^\circ\text{C}$	140 (100)	A
$I_{FM} = -I_{CM}$	$T_h = 25 (70)^\circ\text{C}$, $t_p < 1 \text{ ms}$	360 (260)	A
I_{FSM}	$t_p = 10 \text{ ms}$; sin.; $T_j = 150^\circ\text{C}$	1450	A

Characteristics		$T_{case} = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$; $I_C = \text{mA}$	5,2	5,8	6,4	V
I_{CES}	$V_{GE} = 0$; $V_{CE} = V_{CES}$; $T_j = 25 (125)^\circ\text{C}$				mA
V_{CEO}	$V_{GE} = 0 \text{ V}$; $T_j = 25 (125)^\circ\text{C}$		1 (0,9)	1,2 (1,1)	V
r_{CE}	$V_{GE} = \text{V}$; $T_j = ^\circ\text{C}$		5 (7,5)	6,3	m Ω
V_{CEsat}	$I_C = 200 \text{ A}$; $V_{GE} = 15 \text{ V}$; $T_j = 25 (125)^\circ\text{C}$ on chip level		2 (2,4)	2,45	V
C_{ies}	$V_{GE} = ; V_{CE} = \text{V}$; $f = \text{MHz}$				nF
C_{oes}	$V_{GE} = ; V_{CE} = \text{V}$; $f = \text{MHz}$				nF
C_{res}	$V_{GE} = ; V_{CE} = \text{V}$; $f = \text{MHz}$				nF
L_{CE}	$T_c = ^\circ\text{C}$				nH
$R_{CC'+EE'}$					m Ω
$t_{d(on)}$	$V_{CC} = 1200 \text{ V}$				ns
t_r	$I_C = 200 \text{ A}$				ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 12 \Omega$				ns
t_f	$T_j = 125^\circ\text{C}$				ns
$E_{on} (E_{off})$	$V_{GE} \pm 15 \text{ V}$		120 (80)		mJ
Inverse diode					
$V_F = V_{EC}$	$I_F = 200 \text{ A}$; $V_{GE} = 0 \text{ V}$; $T_j = 25 (125)^\circ\text{C}$				V
V_{TO}	$T_j = 25 (125)^\circ\text{C}$				V
r_T	$T_j = 25 (125)^\circ\text{C}$				V
I_{RRM}	$I_F = 200 \text{ A}$; $T_j = 125^\circ\text{C}$				A
Q_{rr}	$V_{GE} = 0 \text{ V}$ di/dt = A/ μs				μC
E_{rr}	$R_{Gon} = R_{Goff} =$				mJ
Thermal characteristics					
R_{thjh}	per IGBT			0,25	K/W
R_{thjh}	per FWD			0,45	K/W
Temperature Sensor					
R_{TS}	$T = 25 (100)^\circ\text{C}$		1 (1,67)		k Ω
tolerance	$T = 25 (100)^\circ\text{C}$		3 (2)		%
Mechanical data					
M_1	to heatsink (M5)	2		3	Nm
M_2	for terminals (M6)	4		5	Nm
w				310	g

SKiM 180GD176D ...



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.